

M. Yasuda, et al.
USSN 10/040,804
Page 2

been inadvertently overlooked and is required. As provided below, charge Deposit Account **04-1105** for any required fee.

Please amend the subject application as follows:

IN THE CLAIMS

Please **cancel** claims 1-5 without prejudice.

SUMMARY OF CLAIM STATUS

Claims 1-5 (canceled herein)

Claim 6 (previously amended)

6. A method of mounting a semiconductor device on a substrate, comprising the steps of:

forming a composite connection member formed of a core and a conductor covering said core on a first electrode of said semiconductor device;

forming a single-layer connection member formed of a conductor on a second electrode of said semiconductor device;

forming an auxiliary connection part in contact with an upper side of one of the first electrode and the second electrode of said substrate, said auxiliary connection part being formed of a low melting-point conductor having a melting point of at most a melting point of said conductor covering said core; and

matching respective positions of said auxiliary connection part and said composite connection material to bring into contact said auxiliary connection part and said composite connection material, and heating to connect said auxiliary connection part and said composite connection material.

Claims 7-9 (original)

7. The method of mounting a semiconductor device according to claim 6, wherein

said auxiliary connection part on the electrode of said substrate is greater in volume than said conductor of said composite connection material on the electrode of said semiconductor device.

8. A mounting structure for mounting a semiconductor device, that is connected to a substrate via a plurality of connection materials, wherein

said plurality of connection materials are constituted of a first type of connection material formed of a core and a conductor covering said core and a second type of connection material formed of a conductor.

9. A mounting structure for mounting a semiconductor device, that is connected to a substrate via a composite connection material formed of a core and a conductor covering said core, wherein

said composite connection material has a substrate contact portion contacting said substrate and an electrode contact portion contacting an electrode of said semiconductor device, and melting point of said substrate contact portion is lower than that of said electrode contact portion.



Attorney Docket No. 56,677 (70551)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S): M. Yasuda, et al. CONFIRMATION No.: 2892
SERIAL NO.: 10/040,804 GROUP: 2827
FILED: November 8, 2001 EXAMINER: Norris, J.
FOR: ELECTRONIC COMPONENT AND METHOD AND STRUCTURE
FOR MOUNTING SEMICONDUCTOR DEVICE

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: **Mail Stop AF**, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on July 11, 2003.

By: Eileen M. Woodbury
Eileen M. Woodbury

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

AMENDMENT AFTER FINAL PURSUANT TO 37 CFR § 1.116

In response to an Official Action mailed February 13, 2003 currently outstanding with respect to the captioned application, which the Examiner has designated as FINAL, and an Advisory Action mailed July 1, 2003, the Applicants respectfully request that the subject application be amended.

The Applicants believe that a two-month extension of time is required since this response is being filed within two months of the expiration of the specified, statutory shortened time period. The Applicants, however, conditionally petition for a further extension of time to provide for the possibility that such a petition has